

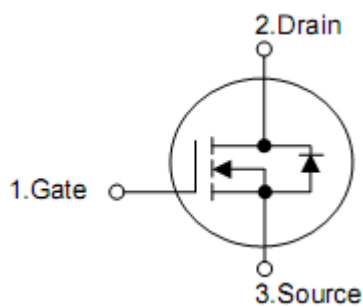
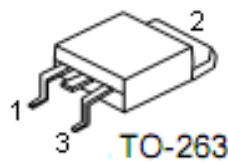
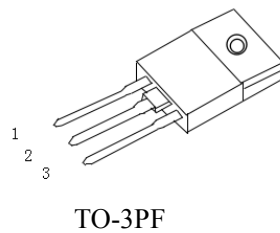
1. Product Features

- High speed switching
- $R_{DS(ON),typ.}=6.5\Omega@V_{GS}=10V$
- Full isolated plastic package

2. Applications

- Switching applications

3. Pin configuration



| Pin | Function |
|-----|----------|
| 1 | Gate |
| 2 | Drain |
| 3 | Source |

4. Ordering Information

| Part Number | Package | Brand |
|-------------|---------|-------|
| KNL42150A | TO-3PF | KIA |
| KNB42150A | TO-263 | KIA |

5. Absolute maximum ratings

(T_C= 25 °C , unless otherwise specified)

| Symbol | Parameter | KNL42150A | Unit |
|-------------------|---------------------------------------------------------------------------|------------|------|
| V _{DSS} | Drain-to-Source Voltage T _J =25 °C | 1500 | V |
| V _{GSS} | Gate-to-Source Voltage | ±30 | |
| I _D | Continuous Drain Current @ T _C =25 °C | 3.0 | A |
| | Continuous Drain Current @ T _C =100 °C | 1.6 | |
| I _{DM} | Pulsed Drain Current at V _{GS} =10V Limited by T _{Jmax} | 10 | |
| E _{AS} | Single Pulse Avalanche Energy(V _{DD} =50V) | 450 | mJ |
| P _D | Maximum Power Dissipation | 63 | W |
| T _{Jmax} | Max. Junction Temperature | 150 | °C |
| T _{STG} | Storage Temperature Range | -55 to 150 | |

6. Thermal characteristics

| Symbol | Parameter | KNL42150 | Unit |
|------------------|-----------------------------------------|----------|-------|
| R _{θJC} | Thermal Resistance, Junction-to-Case | 2 | °C /W |
| R _{θJA} | Thermal Resistance, Junction-to-Ambient | 50 | |

7. Electrical characteristics

| (T _J =25°C, unless otherwise specified) | | | | | | | |
|----------------------------------------------------|-----------------------------------|----------------------------------------------------------------------------------------------------------------------|----------------------|------|------|------|----|
| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit | |
| B _V DSS | Drain-to-Source Breakdown Voltage | V _{GS} =0V, I _D =1mA | 1500 | -- | -- | V | |
| R _{DS(ON)} | Drain-to-Source ON Resistance | V _{GS} =10V, I _D =1.3A | | 6.5 | 9 | Ω | |
| I _{DSS} | Drain-to-Source Leakage Current | V _{DS} =1500V, V _{GS} =0V | -- | -- | 20 | μA | |
| I _{GSS} | Gate-to-Source Leakage Current | V _{GS} =±20V, V _{DS} =0V | -100 | -- | 100 | nA | |
| R _{gint} | Integrated Gate Resistor | | -- | 2 | -- | Ω | |
| V _{GS(TH)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250μA | 3 | 4 | 5 | V | |
| C _{iss} | Input Capacitance | V _{GS} =0V, V _{DS} =25V, f=1.0MHZ | -- | 1500 | -- | pF | |
| C _{rss} | Reverse Transfer Capacitance | | -- | 11 | -- | | |
| C _{oss} | Output Capacitance | | -- | 88 | -- | | |
| Q _g | Total Gate Charge | V _{DD} =1200V, I _D =2.5A, V _{GS} =10V | -- | 35 | -- | nC | |
| Q _{gs} | Gate-to-Source Charge | | -- | 6 | -- | | |
| Q _{gd} | Gate-to-Drain (Miller) Charge | | -- | 20 | -- | | |
| t _{d(ON)} | Turn-on Delay Time | V _{DD} =750V, I _D =1.25A, R _G =4.7Ω V _{GS} =10V (Resistive Load) | T _J =25°C | -- | 30 | -- | nS |
| t _{rise} | Rise Time | | | -- | 65 | -- | |
| t _{d(OFF)} | Turn-Off Delay Time | | | -- | 45 | -- | |
| t _{fall} | Fall Time | | | -- | 60 | -- | |
| I _{SD} | Continuous Source Current | | -- | -- | 2.8 | A | |
| V _{SD} | Forward Voltage | I _S =2.5A, V _{GS} =0V | -- | - | 1.6 | V | |
| t _{rr} | Reverse recovery time | V _{GS} =0V, I _F =2.5A, diF/dt=-100A/μs | -- | 410 | -- | ns | |
| Q _{rr} | Reverse recovery charge | | -- | 2280 | -- | nC | |

8. Test circuits and waveforms

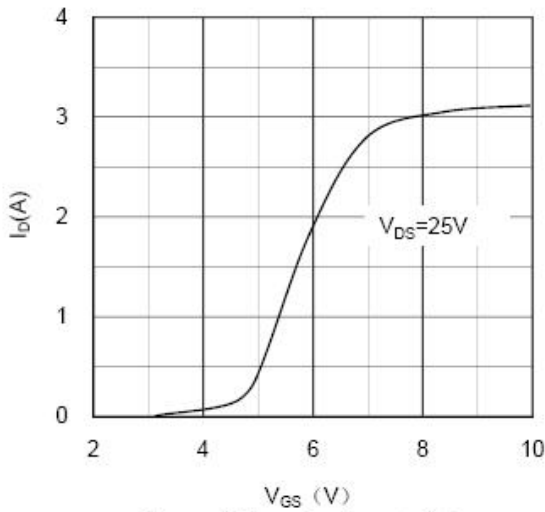


Figure 1. Transfer characteristics

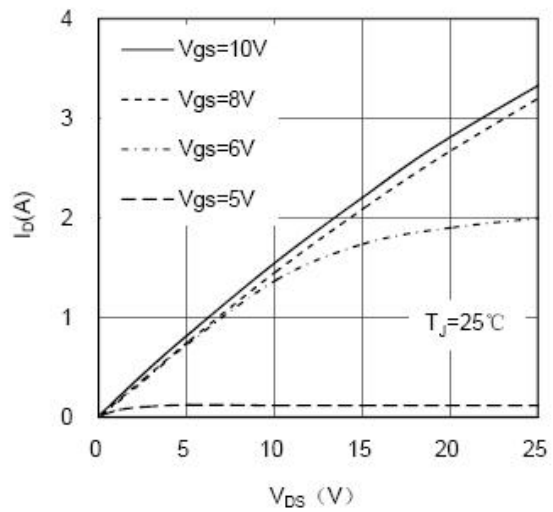


Figure 2. Typical Output Characteristics

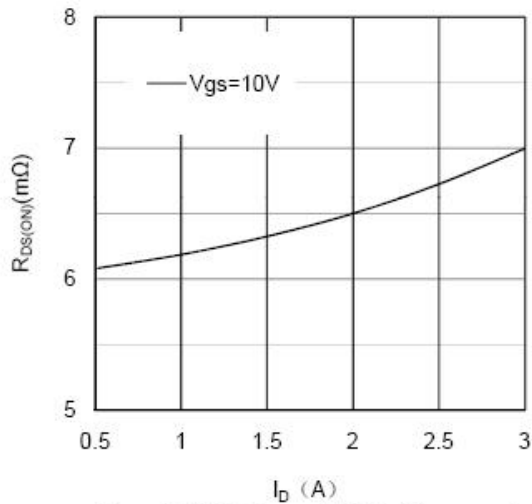


Figure 3. Drain-Source ON Resistance vs I_D

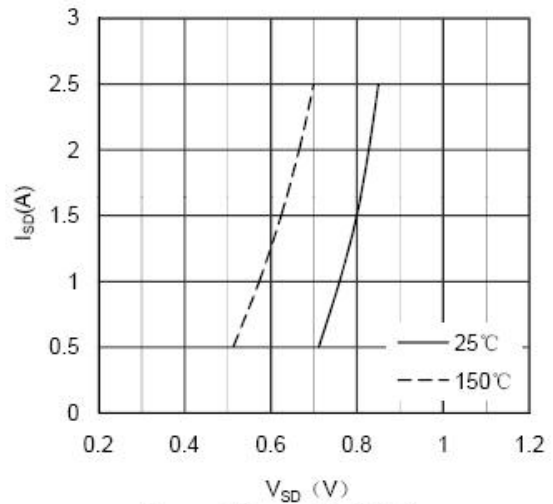


Figure 4. Source-Drain Voltage

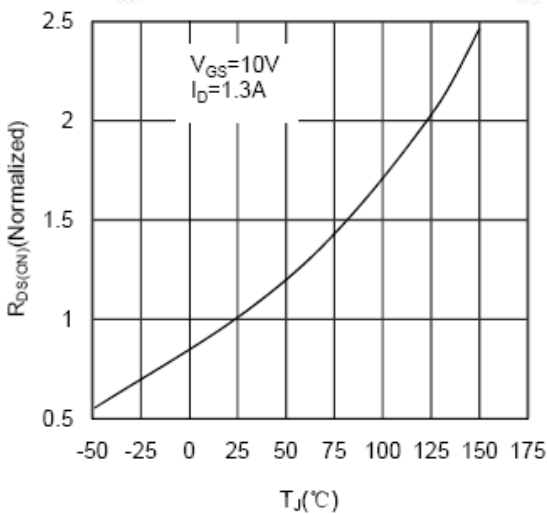


Figure 5. Drain-Source ON Resistance vs Junction Temperature

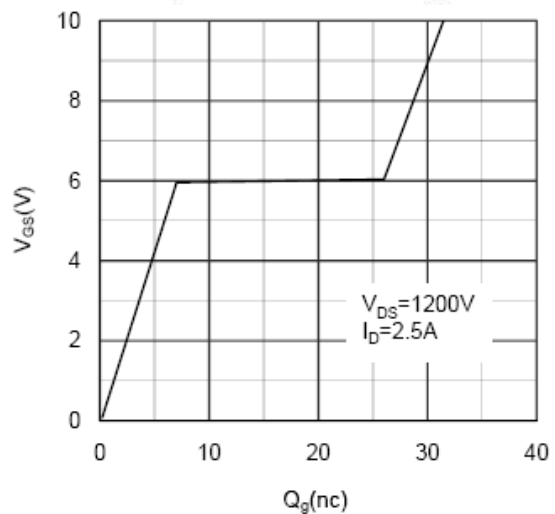


Figure 6. Gate Charge characteristics

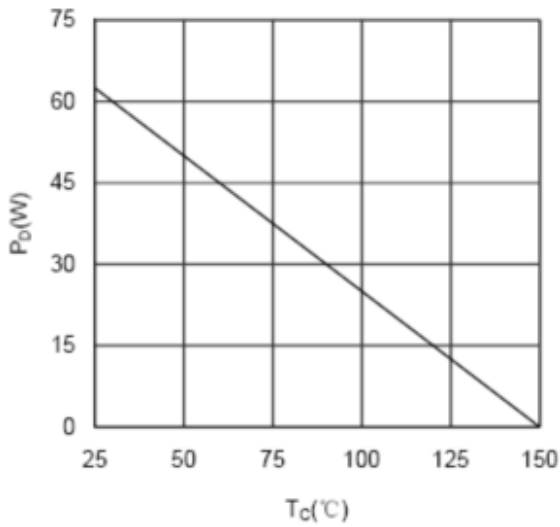


Figure 7. Maximum Power Dissipation vs Case Temperature

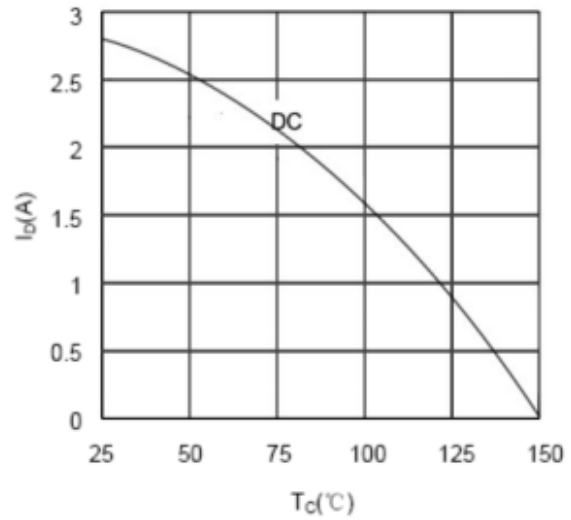


Figure 8. Maximum Continuous Drain Current vs Case Temperature

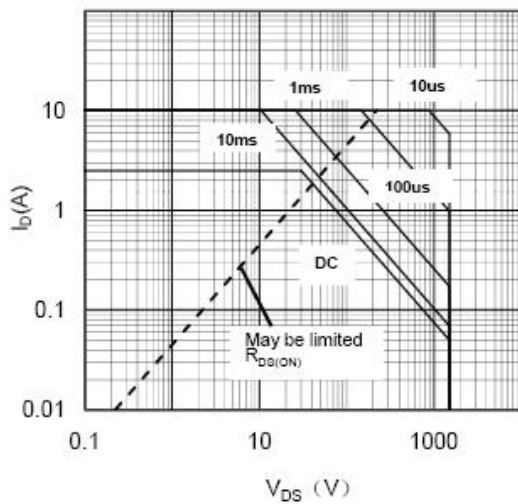


Figure 9. Maximum Forward Safe Operation Area

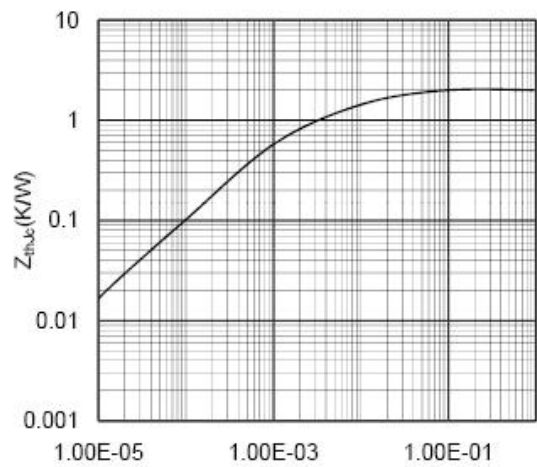


Figure 10. Transient Thermal Impedance